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	DW PACKAGE (TOP VIEW)						
Specifications for Clock Driver	1Y [1 2Y [2	20 1A					
• Operates at 3.3-V V _{CC}	2Y [] 2 3Y [] 3	19 2A 18 3A					
 Flow-Through Architecture Optimizes 	GND 4	17 NC					
PCB Layout	GND 🛛 5	16 🛛 V _{CC}					
Center-Pin V _{CC} and GND Pin	GND 🛿 6	15 🛛 V _{CC}					
Configurations Minimize High-Speed	GND [7	14 🛛 NC					
Switching Noise	4Y [8	13 🛛 4A					
EPIC [™] (Enhanced-Performance Implanted	5Y 🛿 9	12 🛛 5A					
CMOS) 1-µm Process	6Y 🛛 10	11 6A					
• 500-mA Typical Latch-Up Immunity	NC – No inte	rnal connection					

at 125°C

NC – No internal connection

• Packaged in Plastic Small-Outline Package

description

The CDC203 contains six independent inverters. The device performs the Boolean function $Y = \overline{A}$. It is designed specifically for applications requiring low skew between switching outputs.

The CDC203 is characterized for operation from 25°C to 70°C.

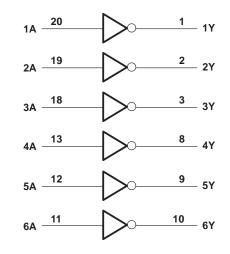
FUNCTION TABLE							
INPUT OUTPUT A Y							
Н	L						
L	н						

logic symbol[†]

1A	20	1	► <u>1</u> 1Y
	19		2 2Y
2A	18		l 3
3A	13		8 4Y
4A	12		9
5A 6A	11		10 5Y
0A			61

⁺ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions

			MIN	NOM	MAX	UNIT
VCC	Supply voltage			3.3	3.6	V
V	/IH High-level input voltage	V _{CC} = 3 V	2.1			V
۲IH		V _{CC} = 3.6 V	2.5			v
\/	Low-level input voltage	$V_{CC} = 3 V$			0.9	V
VIL	Low-level input voltage	V _{CC} = 3.6 V			1.1	v
VI	Input voltage	-	0		VCC	V
VO	Output voltage		0		VCC	V
		V _{CC} = 3 V			-12	mA
ЮН	High-level output current	V _{CC} = 3.6 V			-12	mA
1		V _{CC} = 3 V			12	A
IOL	OL Low-level output current	V _{CC} = 3.6 V			12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate				10	ns/V
fclock	clock Input clock frequency				40	MHz
T _A			25		70	°C



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electrical characteristics	over	recommended	operating	free-air	temperature	range	(unless
otherwise noted)					-	•	

PARAMETER	TEST CONDITIONS	Vee	TA = 25°C		;	MIN	мах	UNIT
	TEST CONDITIONS	Vcc	MIN	TYP	MAX	IVIIIN	MAX	UNIT
	1eu - 50 11A	3 V	2.9			2.9		
Veri	I _{OH} = - 50 μA	3.6 V	3.5			3.5		v
VOH	I _{OH} = - 12 mA	3 V	2.58			2.48		
		3.6 V	3.18			3.08		
Vol	I _{OL} = 50 μA	3 V			0.1		0.1	V
		3.6 V			0.1		0.1	
	40	3 V			0.36		0.44	
	I _{OL} = 12 mA	3.6 V			0.36		0.44	
lj	$V_I = V_{CC}$ or GND	3.6 V			±0.1		±1	μΑ
ICC	$V_{I} = V_{CC} \text{ or GND}, \qquad I_{O} = 0$	3.6 V			4		40	μΑ
Ci	$V_I = V_{CC}$ or GND	3.3 V		4				pF

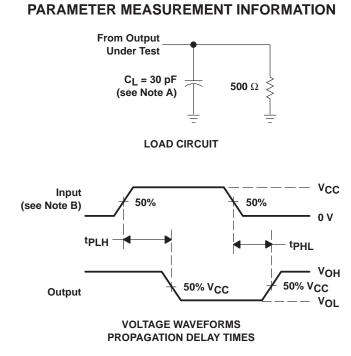
switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (see Note 3 and Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	МАХ	UNIT
^t PLH	A	×	3.5	6.1	
^t PHL	A	1	3.5	6.1	ns
^t sk(o)	A	Y		0.7	ns

NOTE 3: All specifications are valid only for all outputs switching in phase simultaneously.



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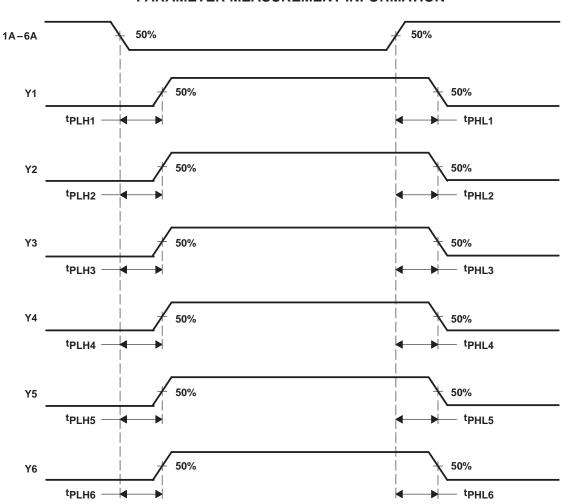
NOTES: A. C_L includes probe and jig capacitance.

- B. Input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f = 3 ns, t_f = 3 ns.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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PARAMETER MEASUREMENT INFORMATION

NOTE A: Output skew, t_{Sk(0)}, is calculated as the greater of:
 The difference between the fastest and slowest of t_{PLHn} (n = 1, 2, ..., 6)
 The difference between the fastest and slowest of t_{PHLn} (n = 1, 2, ..., 6)

Figure 2. Waveforms for Calculation of tsk(o)



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